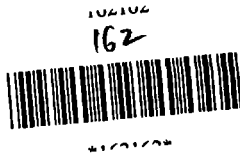


TIN PLATING METHOD

ABSTRACT OF THE DISCLOSURE

Tin deposits having greatly reduced whisker formation are provided. Methods of depositing tin layers or films having a reduced tendency to form whiskers are also provided.

FIG. 2



G00002